

General Description

The G15P04 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as -4.5V. This device is suitable for use as a wide variety of applications.

Features

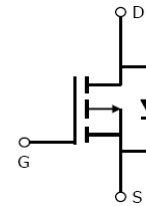


V_{DSS}	$R_{DS(ON)}$ @-4.5V(Typ)	$R_{DS(ON)}$ @-10V(Typ)	I_D
-40V	50m Ω	28m Ω	-15A

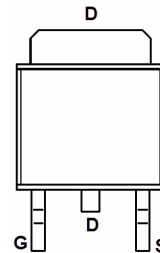
- High Power and current handling capability
- Lead free product is acquired
- Surface Mount Package

Application

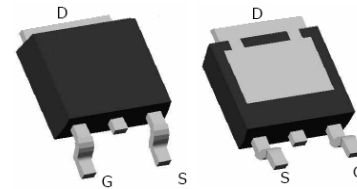
- PWM applications
- Load switch
- Power management



Schematic Diagram



Marking and pin Assignment



TO-252

Table 1. Absolute Maximum Ratings ($T_A=25^\circ\text{C}$)

Symbol	Parameter	Value	Unit
V_{DS}	Drain-Source Voltage ($V_{GS}=0V$)	-40	V
V_{GS}	Gate-Source Voltage ($V_{DS}=0V$)	± 20	V
I_D	Drain Current-Continuous($T_c=25^\circ\text{C}$)	-15	A
	Drain Current-Continuous($T_c=100^\circ\text{C}$)	-12	A
$I_{DM (pluse)}$	Drain Current-Continuous@ Current-Pulsed (Note 1)	-35	A
P_D	Maximum Power Dissipation($T_c=25^\circ\text{C}$)	40	W
	Maximum Power Dissipation($T_c=100^\circ\text{C}$)	20	W
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55 To 175	$^\circ\text{C}$

Table 2. Thermal Characteristic

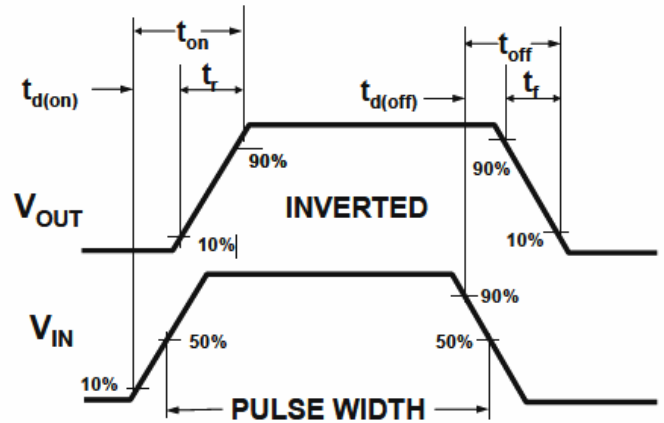
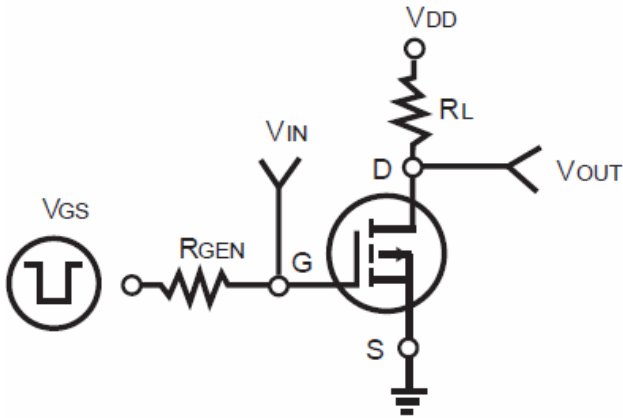
Symbol	Parameter	Value	Unit
$R_{\theta JC}$	Thermal Resistance,Junction-to-Case	3.75	$^\circ\text{C/W}$

Table 3. Electrical Characteristics (TA=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250μA	-40	-43		V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-32V, V _{GS} =0V			-1	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±20V, V _{DS} =0V			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250μA	-1	-2	-3	V
g _{FS}	Forward Transconductance	V _{DS} =-5V, I _D =-10A		25		S
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =-10V, I _D =-15A		28	39	mΩ
		V _{GS} =-4.5V, I _D =-10A		50	70	mΩ
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =-25V, V _{GS} =0V, f=1.0MHz		840		pF
C _{oss}	Output Capacitance			92		pF
C _{rss}	Reverse Transfer Capacitance			60		pF
Switching Times						
t _{d(on)}	Turn-on Delay Time	V _{GS} =-10V, V _{DS} =-20V, R _L =1.6Ω, R _{GEN} =3Ω		6		nS
t _r	Turn-on Rise Time			9		nS
t _{d(off)}	Turn-Off Delay Time			45		nS
t _f	Turn-Off Fall Time			41		nS
Q _g	Total Gate Charge	V _{GS} =-10V, V _{DS} =-20V, I _D =-15A		16		nC
Q _{gs}	Gate-Source Charge			3.8		nC
Q _{gd}	Gate-Drain Charge			3.5		nC
Source-Drain Diode Characteristics						
I _{SD}	Source-Drain Current(Body Diode)				-15	A
V _{SD}	Forward on Voltage	V _{GS} =0V, I _s =-15A			-1.2	V

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

Switch Time Test Circuit and Switching Waveforms:



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (Curves)

Figure1. Power Dissipation

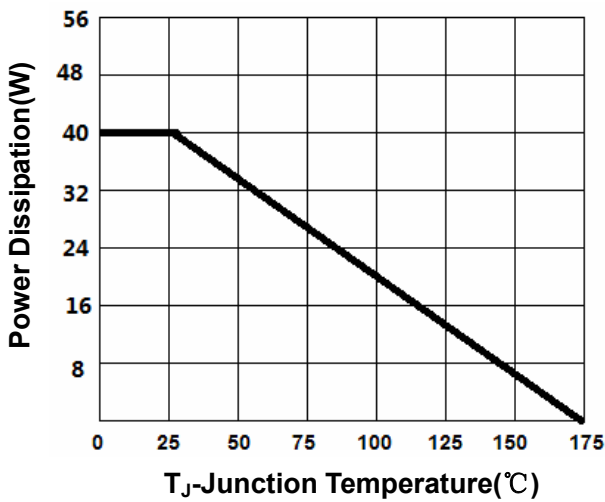


Figure2. Drain Current

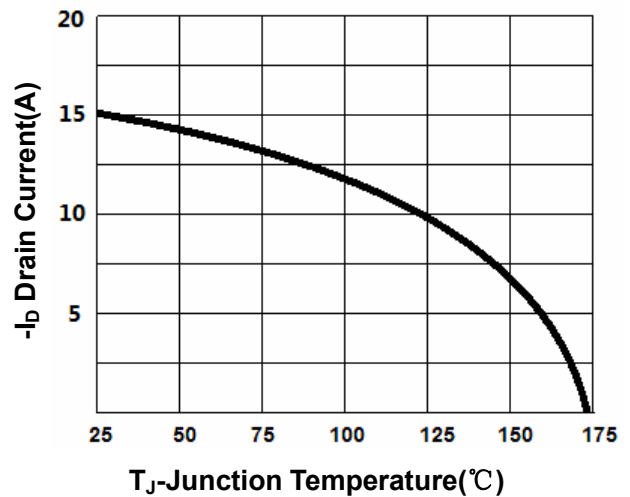


Figure3. Output Characteristics

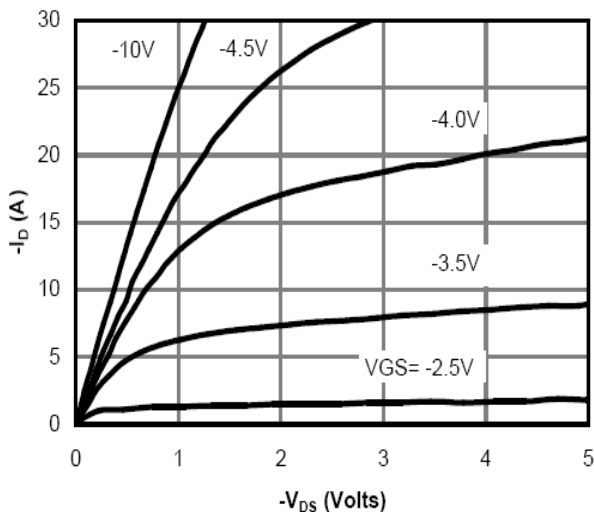


Figure4. Transfer Characteristics

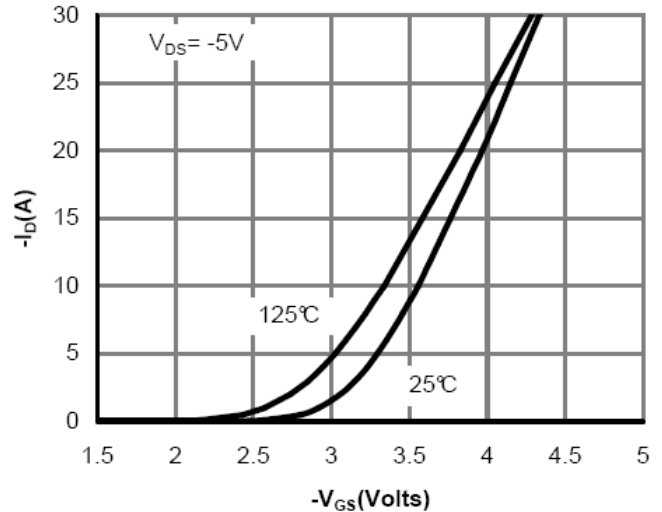


Figure5. Capacitance

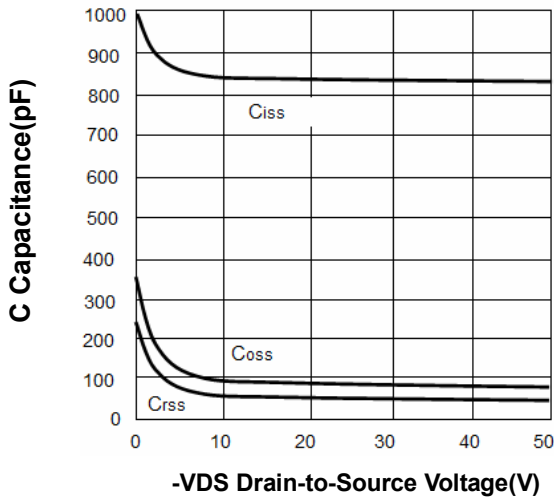


Figure6. $R_{DS(ON)}$ vs Junction Temperature

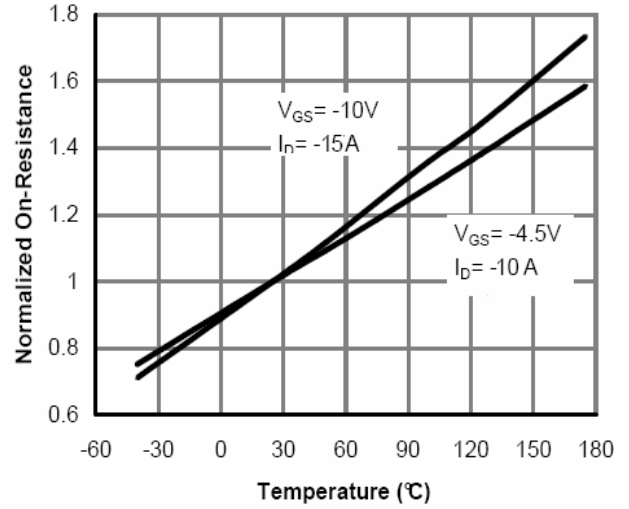


Figure7. $V_{GS(th)}$ vs Junction Temperature

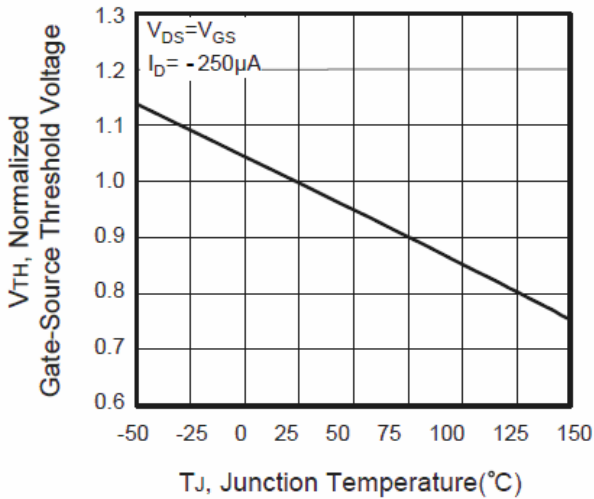


Figure8. Gate Charge Waveforms

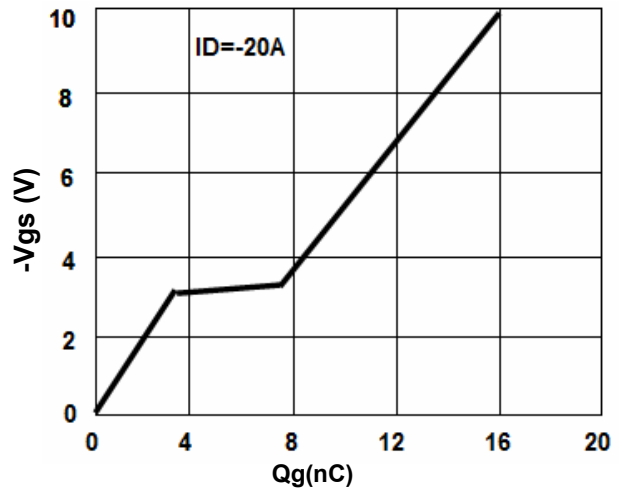


Figure9. Normalized Maximum Transient Thermal Impedance

